

Japan PI&C Committee Meeting Summary and Minutes

Japan Standards Summer Meetings 2013
June 6, 2013, 13:30-17:00
JPR Bldg., Conference Room1, SEMI Japan Office, Tokyo, Japan

Next Committee Meeting

September 4, 2013, 13:30-17:00 Japan Standard Time
Japan Standards Fall Meetings 2013, Tokyo, Japan

Committee Announcements (optional)

None

Table 1 Meeting Attendees

Co-Chairs: Tsuyoshi Nagashima (Miraial), Tsutomu Okabe (TDK), Kenji Yamagata (Daifuku)

SEMI Staff: Hirofumi Kanno

<i>Company</i>	<i>Last</i>	<i>First</i>	<i>Company</i>	<i>Last</i>	<i>First</i>
TDK	Okabe	Tsutomu	Daifuku	Yamagata	Kenji
Hitachi Kokusai Electric	Matsuda	Mitsuhiro	Consultant	Kumai	Sadao
Sinfonia Technology	Otani	Mikio	Consultant	Shimizu	Yasuhiro
Sinfonia Technology	Taniyama	Yasushi	Muratec	Murata	Masanao
Intel	Nojima	Takao	Tokyo Electron	Mashiro	Supika
SUMCO	Nakai	Tetsuya	Acteon	Komatsu	Shoji

Table 2 Leadership Changes

None

Table 3 Ballot Results (or move to Section 4, Ballot Review)

None

Table 4 Authorized Ballots (or move to Section 7, New Business)

None

Table 5 Authorized Activities (or move to Section 7, New Business)

#	Type	SC/TF/WG	Details
5524	SNARF	450 mm AMHS Task Force	<Revised SNARF Approval> Revision to SEMI E156-0710, Mechanical Specification for 450 mm AMHS Sticker to Transport Interface
5632	SNARF	450 mm AMHS Task Force	New Standard: Specification for Signal Tower for 450mm AMHS

Note: SNARFs and TFOFs are available for review on the SEMI Web site at:

<http://downloads.semi.org/web/wstdsbal.nsf/TFOFSNARF>

Table 6 New Action Items (or move to Section 8, Action Item Review)

Item #	Assigned to	Details
130606-1	Supika Mashiro	Supika Mashiro to ask the EHS Committee for feedback about the document activity of Specification for Signal Tower for 450mm AMHS through PI&C Liaison report to the EHS

Table 6 New Action Items (or move to Section 8, Action Item Review)

<i>Item #</i>	<i>Assigned to</i>	<i>Details</i>
		Committee.

Table 7 Previous Meeting Actions Items (or move to Section 8, Action item Review)

None

1 Welcome, Reminders, and Introductions

Tsuyoshi Nagashima called the meeting to order at 13:30. The meeting reminders on antitrust issues, intellectual property issues and holding meetings with international attendance were reviewed. Attendees introduced themselves.

2 Review of Previous Meeting Minutes

The committee reviewed the minutes of the previous meeting.

Motion: Approve the minutes of the previous meeting.

By / 2nd: Kenji Yamagata / Daifuku, Mitsuhiro Matsuda / Hitachi Kokusai Electric

Discussion: None

Vote: 10:0

Attachment: 01, previous minutes

3 Liaison Reports

3.1 Europe Equipment Automation Committee

Hirofumi Kanno (SEMI) reported for the Europe Equipment Automation Committee. Of note:

- Leadership
- Committee Organization
- Meeting Information
 - Last Meeting: Oct 2012 – SEMICON Europa 2012
 - Next Meeting: 7-10 Oct, 2013 – SEMICON Europa 2013
- Activity Highlights

Attachment: 02, EA Liaison Report_April 2013

3.2 North America PI&C Committee

Hirofumi Kanno (SEMI) reported for the North America PI&C Committee. Of note:

- Leadership
- Organization Chart
- Meeting Information
 - Last meeting: April 3, 2013 @ NA Standards Spring 2013 Meetings
 - Next meeting: July 10, 2013 @ SEMICON West 2013
- Ballot Results

- New Activities
- Current/Upcoming Ballots
- Task Force Reports
- Next Meeting Schedule

Attachment: 03, NA PIC Report June 2013 MT

3.3 SEMI Staff Report

Hirofumi Kanno (SEMI) gave the SEMI Staff Report. Of note:

- Global SEMI Events
- Standards Meetings during SEMICON West
- Ballot Critical Dates
- Publication Update
- ISC A&R SC Summary February 2013
- Recent Regulations & Procedure Guide Revisions
- Contact Information

Attachment: 04 SEMI Staff Report 2013 June R1.0

4 Subcommittee & Task Force Reports

4.1 Global PIC Standards Maintenance Task Force

Shoji Komatsu (Acteon) reported that there was no update.

4.2 450 mm International PIC Task Force

Shoji Komatsu (Acteon) reported for the Task Force. The TF reviewed the proposed additions of the robot pocket space to loadport standards:

- The robot pocket space under the raised metal floor (RMF) is for EFEM robot ONLY.
- The ybackpocket = EFEMsupp has to be minimize.
- This volume is to be made available for equipment (SME) that requires a higher wafer transfer plane.
- The volume is to be used for wafer handling robot clearance only, and not for physical support of the robot or EFEM.
- Include a figure and explanation in Related Information to clarify that this space is not applicable across the board and only should be used for tools that require higher transfer plane, i.e. cluster tools and that the OEM needs to coordinate with end user / device maker for implementation.

4.3 International Process Module Physical Interface Task Force

Supika Mashiro (Tokyo Electron) reported that there was no update. The Task Force plans to have a meeting in the near future.

4.4 450 mm AMHS Task Force

Kenji Yamagata (Daifuku) reported for the Task Force. After transferring the E156 revision work from the 450 mm International PI&C Task Force, the Task Force plans to develop the document.

Kenji Yamagata proposed a revised SNARF for *Revision to SEMI E156-0710, Mechanical Specification for 450 mm AMHS Stocker to Transport Interface*

Motion: Approve the revised SNARF(Doc. 5524) for *Revision to SEMI E156-0710, Mechanical Specification for 450 mm AMHS Stocker to Transport Interface*
By / 2nd: Kenji Yamagata (Daifuku) / Mitsuhiro Matsuda (Hitachi Kokusai Electric)
Discussion: Yasuhiro Shimizu pointed out notation in the SNARF.
Vote: 11:0

Kenji Yamagata proposed a new SNARF for *New Standard: Specification for Signal Tower for 450mm AMHS*

Motion: Approve the New SNARF for *New Standard: Specification for Signal Tower for 450mm AMHS*
By / 2nd: Kenji Yamagata (Daifuku) / Mitsuhiro Matsuda (Hitachi Kokusai Electric)
Discussion: None
Vote: 11:0

Action Item: 130606-01, Supika Mashiro to ask the EHS Committee for feedback about the document activity of *Specification for Signal Tower for 450mm AMHS* through PI&C Liaison report to the EHS Committee.

4.5 International Reticle SMIF Pod & Load Port Interoperability Task Force

Hirofumi Kanno (SEMI) gave the Task Force report instead of Koji Ohyama (Dainichi Shoji).

- Task Force created Related Information to SEMI E19 with list of known sensor positions and advice for sensor implementation
- A brief Related Information to SEMI E19.3, E111 and E112 were created which direct the readers of the standards to the detailed RI in SEMI E19
- Task Force developed 4 ballot documents and submitted them to SEMI HQ on May 15, 2013
- Review of the ballot results will take place in July 8 TF meeting at SEMICON West
- **Attachment:** 05, Reticle Pod LP Interoperability TF Report 2013-06

4.6 (Silicon Wafer Committee) Japan Shipping Box Task Force / International 450 mm Shipping Box Task Force

Yasuhiro Shimizu (Consultant) reported for the Task Forces.

- 450 mm Wafer Shipping System
 - Ballot for a new standard: 450 mm Wafer Shipping System
- Error Correction of SEMI M80-0812
 - M80 Fig. 17 and Fig. 18 show incorrect (BP) reference plane notation.
 - Needs correction for M80

Attachment: 06, SHIPPING BOX TF REPORT 2013_06_06

4.7 Update from Polished /Epi/ASI/AWG TFs(Int'l 450mm related TF) under the global Silicon Wafer Committee
Tetsuya Nakai (SUMCO) gave updates. There were some discussion for 450 mm Notch Less at the previous North America Spring Meeting. A SNARF for 450 mm Notch Less is going to be submitted at SEMICON West 2013. Japan Silicon Wafer Committee members and Japan Traceability Committee members are going to meet on June 18 at SEMI Japan office. Mike Goldstein (Intel), Co-leader of the International 450 mm Wafers Task Force, will join the meeting as well.

5 Old Business

5.1 Announcement of the new co-chair of the Japan PI&C Committee

Hirofumi Kanno addressed the committee on this topic.

6 New Business

6.1 450 mm Standards Seminar

Shoji Komatsu addressed the committee on this topic. Shoji Komatsu proposed to hold the seminar at SEMICON Japan 2013.

Motion: Approve that the committee hold a 450 mm Standards seminar at the SEMICON Japan 2013, Makuhari Messe, Chiba, Japan.

By / 2nd: Shoji Komatsu / Acteon, Mitsuhiro Matsuda / Hitachi Kokusai Electric

Discussion:

- Need to consider the title name for 450 mm Standards seminar since the title name of the 450 mm Standards seminar held last year did not much its scope.
- Talk about the details for the seminar among the co-chairs
- Explore the possibility of joint hosting among other Committees (Japan Silicon Wafer/ Packaging).

Vote: 11:0

6.2 Interoperability Test Group Japan Notch Free (ITG-J NF)

Shoji Komatsu addressed the activity. This group has been organized for notch free interoperability test. The group is not belonging to SEMI Standards Program

7 Action Item Review

7.1 Open Action Items

None

7.2 New Action Items

Hirofumi Kanno (SEMI) reviewed the new action items. These can be found in the New Action Items table at the beginning of these minutes.

8 Next Meeting and Adjournment

The next meeting of the Japan PI&C committee is scheduled for September 4 at Japan Standards Fall Meetings 2013, in SEMI Japan office, Tokyo, Japan.

Respectfully submitted by:
 Hirfoumi Kanno
 Manager
 SEMI Japan
 Phone: +81.3222.5862
 Email: hkanno@semi.org

Minutes approved by:

Tsuyoshi Nagashima (Mirial), Co-chair	<Date approved>
Tsutomu Okabe (TDK), Co-chair	<Date approved>
Kenji Yamagata (Daifuku), Co-chiar	

Table 8 Index of Available Attachments #1

#	<i>Title</i>	#	<i>Title</i>
01	Previous minutes		
02	EA Liaison Report_April 2013		
03	NA PIC Report June 2013 MT		
04	SEMI Staff Report 2013 June R1.0		
05	Reticle Pod LP Interoperability TF Report 2013-06		
06	SHIPPING BOX TF REPORT 2013_06_06		

#1 Due to file size and delivery issues, attachments must be downloaded separately. A .zip file containing all attachments for these minutes is available at www.semi.org. For additional information or to obtain individual attachments, please contact [SEMI Staff Name] at the contact information above.